



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Pirmin Gerhard MUFFLER

Serial No.: 09/727,354

Filing Date: 30 November 2000

Title: METHOD FOR APPLYING A SUBSTRATE

Group No.: 1733

Examiner: Jessica Rossi

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed 13 June 2002, please amend the
subject Patent Application as follows:

In the Specification:

At Page 3, lines 1-11:

P/ PCT International Publication WO 99/25019 describes a special mixture
for mounting and disassembling a semiconductor wafer. German Patent Reference
DE 43 32 488 discloses a foil attached as flat as possible by adhesive force. Also
known are reversible adhesive layers. It has become apparent, that despite expensive
preparation of the wafer substrate, there is an inherent disadvantage in the system.

I hereby certify that this correspondence (along with any paper referred to as being attached or
enclosed) is being deposited with the United States Postal Service as First Class Mail in an
envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

13 NOV 2002

13 NOV 02
Date

Signature